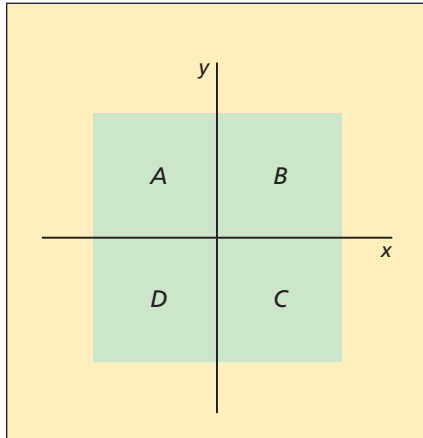# Photodetectors on Coronagraph Mask for Pointing Control

Light from a star under observation would be utilized instead of merely absorbed or suppressed.

NASA's Jet Propulsion Laboratory, Pasadena, California

It has been proposed to install a symmetrical array of photodetectors about the center of the mask of a coronagraph of the type used to search for

A **Square or Rectangular Array** of four photodetectors would provide indications of the *x* and *y* displacements of a star image from the origin, which would lie at the center of a coronagraph mask.

planets orbiting remote stars. The purpose of this installation is to utilize the light from a star under observation as a guide in pointing the telescope. Simple arithmetic processing of the outputs of the photodetectors would provide indications of the lateral position of the center of the mask relative to the center of the image of the star. These indications could serve as pointing-control feedback signals for adjusting the telescope aim to center the image of the star on the mask.

The widths of central mask areas available for placement of photodetectors differ among coronagraph designs, typically ranging upward from about 100 μm. Arrays of photodetectors can readily be placed within areas in this size range. The number of detectors in an array could be as small as 4 or as large as 64. The upper limit on the number of detectors would be determined according to the extent of the occulting pattern and

the number of functionalities, in addition to pointing control, to be served by the array.

In the simplest case, differential position measurements along two orthogonal axes (*x* and *y*) could be effected by use of four photodetectors in a square or rectangular array similar to familiar quadrant detectors. Denoting the reading from each photodetector by the letter designation of the photodetector as shown in the figure, the *x* displacement between the star image and the center of the mask would be proportional to

$$[(A + D) - (B + C)]/(A + B + C + D),$$

while the *y* displacement would be proportional to

$$[(A + B) - (C + D)]/(A + B + C + D).$$

This work was done by Kunjithapatham Balasubramanian of Caltech for NASA's Jet Propulsion Laboratory. Further information is contained in a TSP (see page 1).
NPO-42552

High-Energy-Density, Low-Temperature Li/CF$_x$ Primary Cells

Sub-fluorinated CF$_x$ shows promise as a generic low-temperature cathode material.

NASA's Jet Propulsion Laboratory, Pasadena, California

High-energy-density primary (non-rechargeable) electrochemical cells capable of relatively high discharge currents at temperatures as low as –40 °C have been developed through modification of the chemistry of commercial Li/CF$_x$ cells and batteries. The commercial Li/CF$_x$ units are not suitable for high-current and low-temperature applications because they are current limited and their maximum discharge rates decrease with decreasing temperature.

The term "Li/CF$_x$" refers to an anode made of lithium and a cathode made of a fluorinated carbonaceous material (typically graphite). In commercial cells, *x* typically ranges from 1.05 to 1.1. This cell composition makes it possible to attain specific energies up to 800 Wh/kg, but in order to prevent cell polarization and the consequent large loss of cell capacity, it is typically necessary to keep discharge currents below *C*/50 (where *C* is nu-
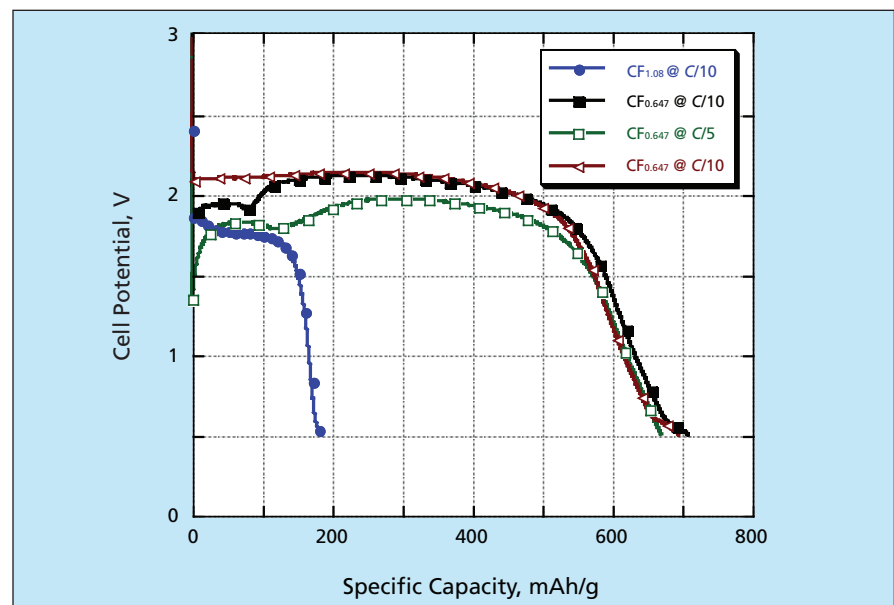
These **Discharge Curves** are typical of results of tests, at a temperature of –40 °C, of cells containing fully fluorinated (CF$_{1.08}$) and sub-fluorinated (CF$_{0.65}$) cathode materials. These tests were performed at a discharge rate of *C*/10 and *C*/5, as labeled. At a potential of 2 V, the CF$_{0.65}$ cathodes exhibited over 3 times the specific capacity of the CF$_{1.08}$ cathode.

merically equal to the current that, flowing during a charge or discharge time of one hour, would integrate to the nominal charge or discharge capacity of a cell). This limitation has been attributed to the low electronic conductivity of CF_x for $x \approx 1$. To some extent, the limitation might be overcome by making cathodes thinner, and some battery manufacturers have obtained promising results using thin cathode structures in spiral configurations.

The present approach includes not only making cathodes relatively thin [$\approx$2 mils ($\approx$0.051 mm)] but also using sub-fluorinated CF_x cathode materials (x <1) in conjunction with electrolytes formulated for use at low temperatures. The reason for choosing sub-fluorinated CF_x cathode materials is that their electronic conductivities are high, relative to those for which x >1. It was known from recent prior research that cells containing sub-fluorinated CF_x cathodes (x between 0.33 and 0.66) are capable of retaining substantial portions of their nominal low-current specific energies when discharged at rates as high as $5C$ at room tempera-

ture. However, until experimental cells were fabricated following the present approach and tested, it was not known whether or to what extent low-temperature performance would be improved.

For the experimental cells, cathodes were fabricated by spray deposition of multiple layers of cathode mixtures onto roughened 1-mil ($\approx$0.025-mm)-thick aluminum-foil current collectors. Each cathode mixture consisted of a CF_x powder and carbon black suspended in a binder/solvent solution of poly(vinylidene fluoride) in N-methyl-2-pyrrolidinone. For some of the cells, the CF_x was sub-fluorinated by various amounts (x = 0.53 or x = 0.65). For other cells, used as controls, a fully fluorinated industrial CF_x (x = 1.08) was used. Each resulting cathode structure, 1 to 3 mils (about 0.025 to 0.076 mm) thick, was vacuum furnace dried, then incorporated into a standard coin cell case along with a separator, lithium foil anode, and an electrolyte consisting of $LiBF_4$ dissolved at a concentration if 0.5 M in an 80/20 DME/PC (dimethoxy ethane/propylene carbon-

ate) solvent mixture. The cells were tested in galvanostatic discharges at room temperature and –40 °C at currents from $2C$ to $C/40$. The fully fluorinated and sub-fluorinated cells performed comparably at rates as high as $2C$ at room temperature. At –40 °C, the sub-fluorinated cells exhibited approximately 3 times the specific capacities of the fully fluorinated cells when discharged at $C/10$ and $C/5$ discharge rates (see figure).

G⁴-FETs as Universal and Programmable Logic Gates

Logic functions could be implemented using fewer active circuit elements.

NASA's Jet Propulsion Laboratory, Pasadena, California

An analysis of a patented generic silicon-on-insulator (SOI) electronic device called a G⁴-FET has revealed that the device could be designed to function as a universal and programmable logic gate. The universality and programmability could be exploited to design logic circuits containing fewer discrete components than are required for conventional transistor-based circuits performing the same logic functions.

A G⁴-FET is a combination of a junction field-effect transistor (JFET) and a metal oxide/semiconductor field-effect transistor (MOSFET) superimposed in a single silicon island and can therefore be regarded as two transistors sharing the same body. A G⁴-FET can also be regarded as a single transistor having four gates: two side junction-based gates, a top MOS gate, and a back gate activated by biasing of the SOI substrate. Each of these gates can be used to control the conduction characteristics of the transistor; this possibility creates new options for designing analog,

radio-frequency, mixed-signal, and digital circuitry.

With proper choice of the specific dimensions for the gates, channels, and ancillary features of the generic G⁴-FET, the device could be made to function as a three-input, one-output logic gate. As illustrated by the truth table in the top part of the figure, the behavior of this logic gate would be the inverse (the NOT) of that of a majority gate. In other words, the device would function as a NOT-majority gate. By simply adding an inverter, one could obtain a majority gate. In contrast, to construct a majority gate in conventional complementary metal oxide/semiconductor (CMOS) circuitry, one would need four three-input AND gates and a four-input OR gate, altogether containing 32 transistors.

The middle part of the figure schematically depicts three ways of realizing an inverter (NOT gate), two ways of realizing an AND gate, and two ways of realizing an OR gate by use of one or two NOT-majority gates. In addition

(not shown in the figure), by using one of the three inputs as a programming or control input that is set to 0 or 1, a NOT-majority could be made to respond to the other inputs as either a NAND or a NOR gate, respectively. Inasmuch as the sets {NOT,AND}, {NOT,OR}, and {NAND,NOR} have previously been shown to be universal (in the sense that any digital computation or logic function could be realized by use of suitable combinations of members of these sets), the possibility of realizing these sets signifies that the NOT-majority gate is also universal.

The bottom part of the figure depicts a full adder, implemented by use of three NOT-majority gates and two inverters, that would put out two one-bit binary numbers in response to three input one-bit binary numbers. The design of this adder exploits the possibility of switching a NOT-majority gate between NAND and NOR functionality to minimize the number of gates needed. In contrast, the simplest implementation of